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Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 61212
Application ID: 10774893
Title of Invention: LEADFRAME FOR
SEMICONDUCTOR PACKAGE
First Named Inventor: HYUNG LEE
Domestic/Foreign Application: Domestic Application
Filing Date: 2004-02-09
Effective Receipt Date: 2004-05-18
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 8761
Attorney Docket Number: AMKOR006C




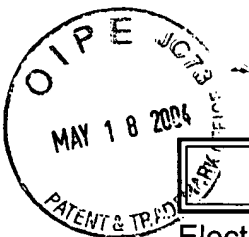
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Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	LEADFRAME FOR SEMICONDUCTOR PACKAGE									
<p>Application Number: 10/774893 </p> <p>Date: 2004-02-09</p> <p>First Named Applicant: HYUNG JU LEE</p> <p>Confirmation Number: 8761</p> <p>Attorney Docket Number: AMKOR006C</p>										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids4-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids4-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids4-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

LEADFRAME FOR SEMICONDUCTOR PACKAGE

Application Number: 10/774893



Confirmation Number: 8761

First Named Applicant: HYUNG LEE

Attorney Docket Number: AMKOR006C

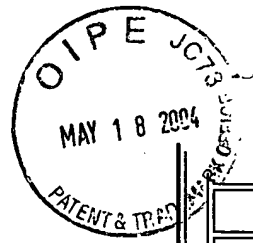
Art Unit: 2811

Search string: (5886398 or 5894108 or 5897339 or 5900676
or 5903049 or 5903050 or 5909053 or 5915998
or 5917242 or 5939779 or 5942794 or 5951305
or 5959356 or 5969426 or 5973388 or 5976912
or 5977613 or 5977615 or 5977630 or 5981314
or 5986333 or 5986885 or 6001671 or 6013947
or 6018189 or 6020625 or 6025640 or 6031279
or 6034423 or RE36613 or 6040626 or 6043430
or 6060768 or 6060769 or 6072228 or 6075284
or 6081029 or 6084310 or 6087715 or 6087722
or 6100594 or 6114752 or 6113474 or 6118174
or 6118184 or 6130115 or 6130473 or RE36907
or 6133623 or 6140154).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date